TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150821000B
Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices
Change Notification / Sample Request

Date: August 08, 2017
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

The purpose of this version B is to cancel this change. We apologize for any inconvenience this may have caused.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150821000B
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CDCV304PW	null
CDCV304PWR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150821000B	**PCN Date:**	Aug. 8, 2017

Title:	Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices

Customer Contact:	PCN Manager	**Dept:**	Quality Services

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is canceled. All affected devices will continue to be assembled and tested using the current site (TI Malaysia).

Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices. Assembly differences are shown in the following table:

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Malaysia	MLA	MY	Kuala Lumpur
ASESH	**ASH**	**CN**	**Shanghai**

Material Differences:

	TI Malaysia	**ASESH**
Mount Compound	4042500	EY1000063
Mold Compound	4206193	EN2000507
Lead Finish	NiPdAu	Matte Sn

Upon expiration of this PCN, TI will combine lead free solutions in a single ***standard part number***, for example; ***CDCV304PW***– can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. ***CDCV304PWG4.”***

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site			
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA	ECAT: G4
ASESH	Assembly Site Origin (22L)	ASO: ASH	ECAT: G3

Sample product shipping label (not actual product label)

ECAT: G4 = NiPdAu
ECAT: G3 = Matte Sn

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: TI Malaysia =K, ASESH = A

Product Affected:

~~CDCV304PW~~	~~CDCV304PWG4~~	~~CDCV304PWR~~	~~CDCV304PWRG4~~

Qualification Report

CDCV304PW: Qualification of alternative Assembly Site (ASESH)

Product Attributes

Attributes	Qual Device: CDCV304
Assembly Site	ASE SHANGHAI (ASESH)
Package Family	TSSOP
Flammability Rating	UL 94 V-0
Wafer Fab Site	ANAM (DONGBU)
Wafer Fab Process	33C10

- QBS: Qual By Similarity
- Qual Device CDCV304 is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCV304
PC	PreCon Level 1	25C	1/280/0
AC	Autoclave 121C	96 Hours	1/80/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/80/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/80/0
MQ	Manufacturability	(per mfg. Site specification)	Pass
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com